

ABSTRACT OF THE DISCLOSURE

MOUNTING METHOD OF IC CHIP AND MANUFACTURING METHOD OF HEAD SUSPENSION ASSEMBLY WITH THE IC CHIP

A method of mounting an IC chip on a suspension having connection pads. The IC chip has a circuit for a thin-film magnetic head element and connection terminals connected to the circuit. The method includes a step of increasing a load applied to the IC chip so that metal bumps formed on the connection terminals press the connection pads formed on the suspension, respectively, and a step of starting application of ultrasonic vibration to the IC chip during the increasing of the load applied to the IC chip.

(Fig. 4)